

FS23

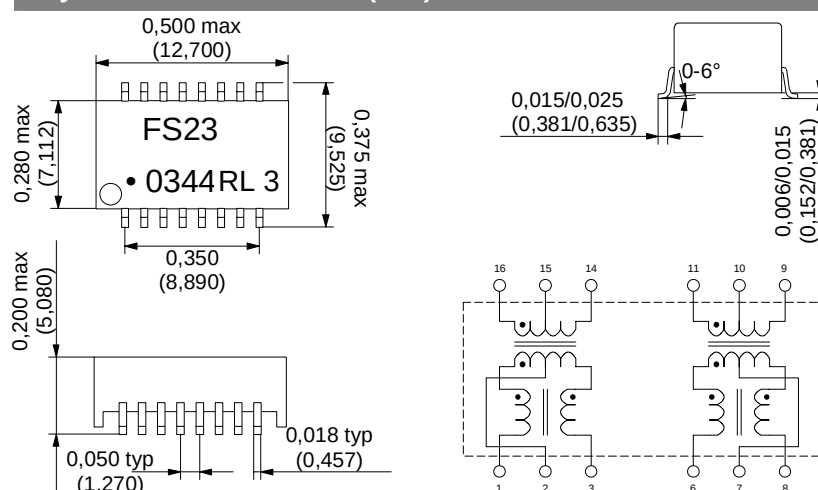
Ethernet Transformer 10/100Base-TX Magnetic Module Meets requirements of IEEE 802.3 IPC@CHIP SC13 compatible

Technical data

Isolation	1,500 Vrms
OCL @100 KHz, 8 mA	350 µH min
CMR (0.1-100 MHz)	-40 dB typ
Cross Talk (0.1-100 MHz)	-40dB min
Insertion Loss (0.1-100 MHz)	-1.1 dB max
Return Loss	
0.5-30 MHz	-18 dB min
40MHz	-15.4 dB min
50MHz	-13.6 dB min
60-80 MHz	-12 dB min
Turn Ratio +/-3%	
(1-3:16-14) / (6-8:11-9)	(1CT:1CT) / (1CT:1CT)
PRI/SEC Cw/w	15 pF typ
PRI LL	0.4 µH max
PRI DDCR	1.5 Ohm max
Operating temperature (T _A)	0°C to +70°C
Package	SOIC 16 (lead free; RoHS compliant marked with RL)
Soldering	IEC J-STD-020C. Reflow soldering only.



Physical dimensions: Inch (mm)



Ordering information

Order-No.: 538431

The following IPC/JEDEC J-STD-020C compatible reflow and wave soldering profiles are recommended for processing Pb-Free surface mount and through-hole products. SMT products are tested to withstand maximum peak temperature up to 260°C.



Maximum duration of peak temperature shall not exceed 10 seconds.
Maximum duration of temperature above 217°C shall not exceed 90 seconds.
Maximum ramp rate up 3°C/down 6°C per second.